

## LQ-BL859140-SRC

40Gb/s 100m QSFP+, Bi-Di, Duplex LC Hot Pluggable, 850/910nm, VCSEL, Multimode

### Features

- Compliant to the 40GbE XLPP1 electrical specification per IEEE 802.3ba-2010
- Compliant to QSFP+ SFF-8436 Specification
- Aggregate bandwidth of > 40Gbps
- Operates at 10.3125 Gbps per electrical channel with 64b/66b encoded data
- QSFP MSA compliant
- Capable of over 100m transmission on OM3 Multimode Fiber (MMF) and 150m on OM4 MMF
- Single +3.3V power supply operating
- Without digital diagnostic functions
- Temperature range 0°C to 70°C
- RoHS Compliant Part
- Utilizes a standard LC duplex fiber cable allowing reuse of existing cable infrastructure

### Applications

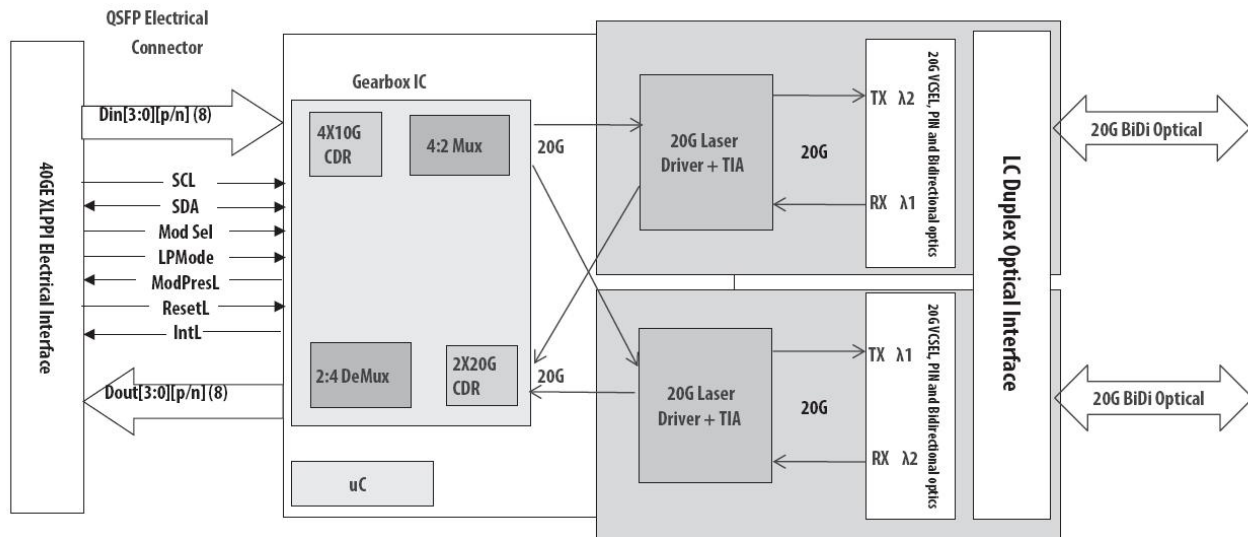
- 40 Gigabit Ethernet interconnects
- Datacom/Telecom switch & router connections
- Data aggregation and backplane applications
- Proprietary protocol and density applications



### Description

It is a Four-Channel Pluggable, LC Duplex, Fiber-Optic QSFP+ Transceiver for 40 Gigabit Ethernet Applications. This transceiver is a high performance module for short-range duplex data communication and interconnect applications. It integrates four electrical data lanes in each direction into transmission over a single LC duplex fiber optic cable. Each electrical lane operates at 10.3125 Gbps and conforms to the 40GE XLPP1 interface. The transceiver internally multiplexes an XLPP1 4x10G interface into two 20Gb/s electrical channels, transmitting and receiving each optically over one simplex LC fiber using bi-directional optics. This results in an aggregate bandwidth of 40Gbps into a duplex LC cable. This allows reuse of the installed LC duplex cabling infrastructure for 40GbE application. Link distances up to 100 m using OM3 and 150m using OM4 optical fiber

are supported. These modules are de- signed to operate over multimode fiber systems using a nominal wavelength of 850nm on one end and 910nm on the other end. The electrical interface uses a 38 contact QSFP+ type edge connector. The optical interface uses a conventional LC duplex connector.



Transceiver Block Diagram

### Absolute Maximum Ratings

Parameter	Symbol	Min.	Typical	Max.	Unit
Storage Temperature	T <sub>S</sub>	-40		+85	°C
Supply Voltage	V <sub>CC</sub> T, R	-0.5		4	V
Relative Humidity	RH	0		85	%

### Recommended Operating Environment

Parameter	Symbol	Min.	Typical	Max.	Unit
Case operating Temperature	T <sub>C</sub>	0		+70	°C
Supply Voltage	V <sub>CCT, R</sub>	+3.13	3.3	+3.47	V
Supply Current	I <sub>CC</sub>			1000	mA
Power Dissipation	PD			3.5	W

**Electrical Characteristics (TOP = 0 to 70 °C, VCC = 3.13 to 3.47 Volts)**

Parameter	Symbol	Min	Typ	Max	Unit	Note
Data Rate per Channel		-	10.3125	11.2	Gbps	
Power Consumption		-	2.5	3.5	W	
Supply Current	Icc		0.75	1.0	A	
Control I/O Voltage-High	VIH	2.0		Vcc	V	
Control I/O Voltage-Low	VIL	0		0.7	V	
Inter-Channel Skew	TSK			150	Ps	
RESETL Duration			10		Us	
RESETL De-assert time				100	ms	
Power On Time				100	ms	
<b>Transmitter</b>						
Single Ended Output Voltage Tolerance		0.3		4	V	1
Common mode Voltage Tolerance		15			mV	
Transmit Input Diff Voltage	VI	120		1200	mV	
Transmit Input Diff Impedance	ZIN	80	100	120		
Data Dependent Input Jitter	DDJ			0.1	UI	
Data Input Total Jitter	TJ			0.28	UI	
<b>Receiver</b>						
Single Ended Output Voltage Tolerance		0.3		4	V	
Rx Output Diff Voltage	Vo		600	800	mV	
Rx Output Rise and Fall Voltage	Tr/Tf			35	ps	1
Total Jitter	TJ			0.7	UI	
Deterministic Jitter	DJ			0.42	UI	

Note:

1. 20~80%

**Optical Parameters(TOP = 0 to 70 °C, VCC = 3.0 to 3.6 Volts)**

Parameter	Symbol	Min	Typ	Max	Unit	Ref.
<b>Transmitter</b>						
Optical Wavelength CH1	$\lambda$	832	850	868	nm	
Optical Wavelength CH2	$\lambda$	882	900	918	nm	
Average Optical Power per Channel	Pavg	-4	0	+5.0	dBm	
Laser Off Power Per Channel	Poff			-30	dBm	
Optical Extinction Ratio	ER	3			dB	
Relative Intensity Noise	Rin			-128	dB/HZ	1
Optical Return Loss Tolerance				12	dB	
<b>Receiver</b>						
Optical Center Wavelength CH1	$\lambda$	882	900	918	nm	
Optical Center Wavelength CH2	$\lambda$	832	850	868	nm	
Receiver Sensitivity per Channel	R		-6		dBm	
Maximum Input Power	P <sub>MAX</sub>	+3			dBm	
Damage Threshold	P <sub>Min</sub>	+7				
Receiver Reflectance	R <sub>Rx</sub>			-12	dB	
LOS De-Assert	LOS <sub>D</sub>			-14	dBm	
LOS Assert	LOS <sub>A</sub>	-30			dBm	
LOS Hysteresis	LOS <sub>H</sub>	0.5			dB	

Note1 2dB Reflection

**Timing for Soft Control and Status Functions**

Parameter	Symbol	Max	Unit	Conditions
Initialization Time	t <sub>init</sub>	2000	ms	Time from power on1, hot plug or rising edge of Reset until the module is fully functional2
Reset Init Assert Time	t <sub>reset_init</sub>	2	$\mu$ s	A Reset is generated by a low level longer than the minimum reset pulse time present on the ResetL pin.
Serial Bus Hardware Ready Time	t <sub>serial</sub>	2000	ms	Time from power on1 until module responds to data transmission over the 2-wire serial bus
Monitor Data Ready Time	t <sub>data</sub>	2000	ms	Time from power on1 to data not ready, bit 0 of Byte 2, deasserted and IntL asserted
Reset Assert Time	t <sub>reset</sub>	2000	ms	Time from rising edge on the ResetL pin until the module is fully functional2

LPMODE Assert Time	ton_LPMODE	100	μs	Time from assertion of LPMODE (Vin:LPMODE =Vih) until module power consumption enters lower Power Level
IntL Assert Time	ton_IntL	200	ms	Time from occurrence of condition triggering IntL until Vout:IntL = Vol
IntL Deassert Time	toff_IntL	500	μs	toff_IntL 500 μs Time from clear on read3 operation of associated flag until Vout:IntL = Voh. This includes deassert times for Rx LOS, Tx Fault and other flag bits.
Rx LOS Assert Time	ton_los	100	ms	Time from Rx LOS state to Rx LOS bit set and IntL asserted
Flag Assert Time	ton_flag	200	ms	Time from occurrence of condition triggering flag to associated flag bit set and IntL asserted
Mask Assert Time	ton_mask	100	ms	Time from mask bit set4 until associated IntL assertion is inhibited
Mask De-assert Time	toff_mask	100	ms	Time from mask bit cleared4 until associated IntL operation resumes
ModSelL Assert Time	ton_ModSelL	100	μs	Time from assertion of ModSelL until module responds to data transmission over the 2-wire serial bus
ModSelL Deassert Time	toff_ModSelL	100	μs	Time from deassertion of ModSelL until the module does not respond to data transmission over the 2-wire serial bus
Power over-ride or Power-set Assert Time	ton_Pdown	100	ms	Time from P_Down bit set 4 until module power consumption enters lower Power Level
Power over-ride or Power-set De-assert Time	Toff down	300	ms	Time from Down bit cleared4 until the module is fully functional3

**Note:**

1. Power on is defined as the instant when supply voltages reach and remain at or above the minimum specified value.
2. Fully functional is defined as IntL asserted due to data not ready bit, bit 0 byte 2 de-asserted.
3. Measured from falling clock edge after stop bit of read transaction.
4. Measured from falling clock edge after stop bit of write transaction

## Pin Assignment

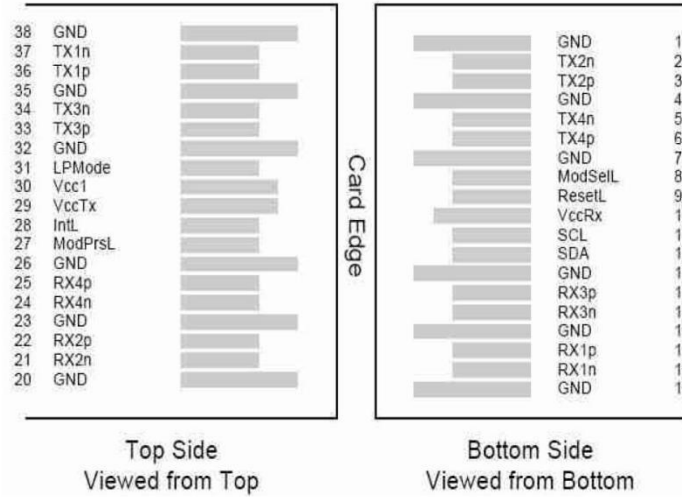


Diagram of Host Board Connector Block Pin Numbers and Name

## Pin Description

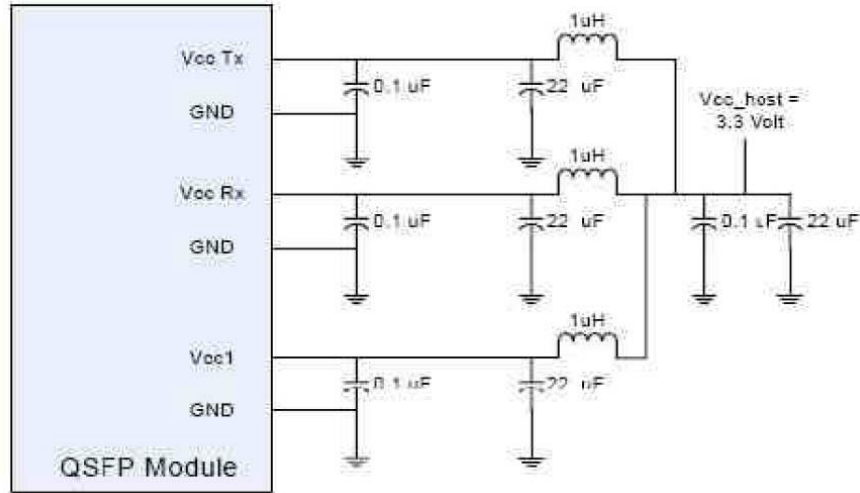
Pin	Logic	Symbol	Name/Description	Ref.
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	
3	CML-I	Tx2p	Transmitter Non-Inverted Data output	
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Output	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Output	
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	
9	LVTTL-I	ResetL	Module Reset	
10		VccRx	+3.3V Power Supply Receiver	2
11	LVCMOS-I/O	SCL	2-Wire Serial Interface Clock	
12	LVCMOS-I/O	SDA	2-Wire Serial Interface Data	
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Inverted Data Output	
15	CML-O	Rx3n	Receiver Non-Inverted Data Output	
16		GND	Ground	1

17	CML-O	Rx1p	Receiver Inverted Data Output	
18	CML-O	Rx1n	Receiver Non-Inverted Data Output	
19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	
26		GND	Ground	1
27	LVTTL-O	ModPrsL	Module Present	
28	LVTTL-O	IntL	Interrupt	
29		VccTx	+3.3V Power Supply Transmitter	2
30		Vcc1	+3.3V Power Supply	2
31	LVTTL-I	LPMode	Low Power Mode	
32		GND	Ground	1
33	CML-I	Tx3p	Transmitter Inverted Data Output	
34	CML-I	Tx3n	Transmitter Non-Inverted Data Output	
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Inverted Data Output	
37	CML-I	Tx1n	Transmitter Non-Inverted Data Output	
38		GND	Ground	1

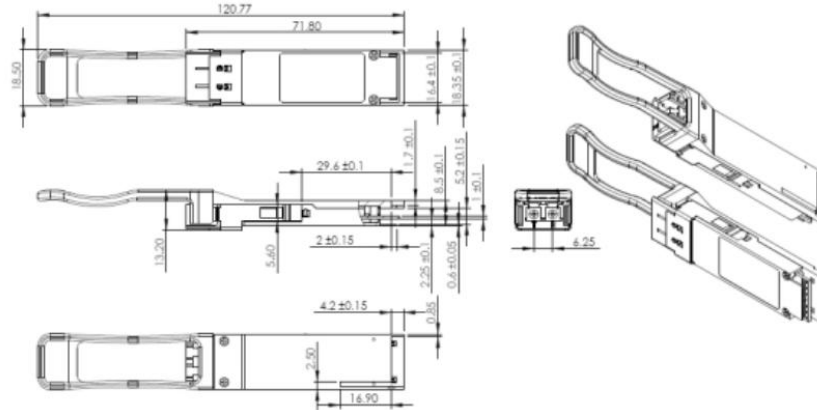
**Notes:**

1. GND is the symbol for single and supply(power) common for QSFP modules, All are common within the QSFP module and all module voltages are referenced to this potential otherwise noted. Connect these directly to the host board signal common ground plane. Laser output disabled on TDIS >2.0V or open, enabled on TDIS <0.8V.
2. VccRx, Vcc1 and VccTx are the receiver and transmitter power suppliers and shall be applied concurrently. Recommended host board power supply filtering is shown below. VccRx, Vcc1 and VccTx may be internally connected within the QSFP transceiver module in any combination. The connector pins are each rated for maximum current of 500mA.

## Recommended Circuit



## Mechanical Dimensions



## Ordering information

Part Number	Product Description
LQ-BL859140-SRC	40G QSFP+ SR BD 850nm OM3 100M /OM4 150M LC MMF, 0°C ~ +70°C